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Applications of "<u>Embedded - Microcontrollers</u>"

ipplier Device Package	PG-LQFP-100-3 https://www.e-xfl.com/product-detail/infineon-technologies/xc226756f66lackxuma
kage / Case	100-LQFP Exposed Pad
inting Type	Surface Mount
erating Temperature	-40°C ~ 125°C (TA)
cillator Type	Internal
ata Converters	A/D 16x8/10b
ltage - Supply (Vcc/Vdd)	3V ~ 5.5V
1 Size	34K x 8
PROM Size	-
gram Memory Type	FLASH
ogram Memory Size	448KB (448K x 8)
ber of I/O	75
ipherals	DMA, I²S, POR, PWM, WDT
nnectivity	CANbus, EBI/EMI, I ² C, LINbus, SPI, SSC, UART/USART, USI
eed	66MHz
re Size	16/32-Bit
re Processor	C166SV2
oduct Status	Discontinued at Digi-Key

XC226x

16/32-Bit Single-Chip Microcontroller with 32-Bit Performance

Microcontrollers





1	Summary of Features
2 2.1	General Device Information 8 Pin Configuration and Definition 9
3 3.1 3.2 3.3 3.4 3.5 3.6 3.7 3.8 3.10 3.11 3.12 3.13 3.14 3.15 3.16 3.17	Functional Description 33 Memory Subsystem and Organization 32 External Bus Controller 35 Central Processing Unit (CPU) 36 Interrupt System 38 On-Chip Debug Support (OCDS) 44 Capture/Compare Unit (CAPCOM2) 45 Capture/Compare Units CCU6x 48 General Purpose Timer (GPT12E) Unit 50 Real Time Clock 54 A/D Converters 56 Universal Serial Interface Channel Modules (USIC) 57 MultiCAN Module 59 Watchdog Timer 67 Clock Generation 67 Parallel Ports 62 Power Management 64 Instruction Set Summary 65
4.1 4.2 4.2.1 4.2.2 4.2.3 4.3 4.4 4.5 4.6.1 4.6.2 4.6.3 4.6.4 4.6.5 4.6.5 4.6.6	Electrical Parameters68General Parameters68DC Parameters72DC Parameters for Upper Voltage Area74DC Parameters for Lower Voltage Area76Power Consumption78Analog/Digital Converter Parameters83System Parameters86Flash Memory Parameters86AC Parameters96Testing Waveforms96Definition of Internal Timing97External Clock Input Parameters96External Bus Timing98Synchronous Serial Interface Timing106JTAG Interface Timing106
5 5.1 5.2	Package and Reliability

Data Sheet 3 V2.1, 2008-08

General Device Information

 Table 4
 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Туре	Function
7	P7.3	O0 / I	St/B	Bit 3 of Port 7, General Purpose Input/Output
	EMUX1	01	St/B	External Analog MUX Control Output 1 (ADC1)
	U0C1_DOUT	O2	St/B	USIC0 Channel 1 Shift Data Output
	U0C0_DOUT	О3	St/B	USIC0 Channel 0 Shift Data Output
	CCU62_ CCPOS1A	I	St/B	CCU62 Position Input 1
	TMS_C	I	St/B	JTAG Test Mode Selection Input
	U0C1_DX0F	I	St/B	USIC0 Channel 1 Shift Data Input
8	P7.1	O0 / I	St/B	Bit 1 of Port 7, General Purpose Input/Output
	EXTCLK	01	St/B	Programmable Clock Signal Output
	TxDC4	O2	St/B	CAN Node 4 Transmit Data Output
	CCU62_ CTRAPA	I	St/B	CCU62 Emergency Trap Input
	BRKIN_C	I	St/B	OCDS Break Signal Input
9	P7.4	O0 / I	St/B	Bit 4 of Port 7, General Purpose Input/Output
	EMUX2	01	St/B	External Analog MUX Control Output 2 (ADC1)
	U0C1_DOUT	O2	St/B	USIC0 Channel 1 Shift Data Output
	U0C1_ SCLKOUT	О3	St/B	USIC0 Channel 1 Shift Clock Output
	CCU62_ CCPOS2A	I	St/B	CCU62 Position Input 2
	TCK_C	I	St/B	JTAG Clock Input
	U0C0_DX0D	I	St/B	USIC0 Channel 0 Shift Data Input
	U0C1_DX1E	I	St/B	USIC0 Channel 1 Shift Clock Input
11	P6.0	O0 / I	St/A	Bit 0 of Port 6, General Purpose Input/Output
	EMUX0	01	St/A	External Analog MUX Control Output 0 (ADC0)
	BRKOUT	О3	St/A	OCDS Break Signal Output
	ADCx_ REQGTyC	I	St/A	External Request Gate Input for ADC0/1
	U1C1_DX0E	I	St/A	USIC1 Channel 1 Shift Data Input

General Device Information

 Table 4
 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Туре	Function
68	P0.5	O0 / I	St/B	Bit 5 of Port 0, General Purpose Input/Output
	U1C1_ SCLKOUT	01	St/B	USIC1 Channel 1 Shift Clock Output
	U1C0_ SELO2	O2	St/B	USIC1 Channel 0 Select/Control 2 Output
	CCU61_ COUT62	О3	St/B	CCU61 Channel 2 Output
	A5	ОН	St/B	External Bus Interface Address Line 5
	U1C1_DX1A	I	St/B	USIC1 Channel 1 Shift Clock Input
	U1C0_DX1C	I	St/B	USIC1 Channel 0 Shift Clock Input
69	P10.4	O0 / I	St/B	Bit 4 of Port 10, General Purpose Input/Output
	U0C0_ SELO3	01	St/B	USIC0 Channel 0 Select/Control 3 Output
	CCU60_ COUT61	O2	St/B	CCU60 Channel 1 Output
	AD4	OH/I	St/B	External Bus Interface Address/Data Line 4
	U0C0_DX2B	I	St/B	USIC0 Channel 0 Shift Control Input
	U0C1_DX2B	I	St/B	USIC0 Channel 1 Shift Control Input
70	P10.5	O0 / I	St/B	Bit 5 of Port 10, General Purpose Input/Output
	U0C1_ SCLKOUT	01	St/B	USIC0 Channel 1 Shift Clock Output
	CCU60_ COUT62	O2	St/B	CCU60 Channel 2 Output
	AD5	OH/I	St/B	External Bus Interface Address/Data Line 5
	U0C1_DX1B	I	St/B	USIC0 Channel 1 Shift Clock Input

Data Sheet 21 V2.1, 2008-08

General Device Information

 Table 4
 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
71	P0.6	O0 / I	St/B	Bit 6 of Port 0, General Purpose Input/Output
	U1C1_DOUT	01	St/B	USIC1 Channel 1 Shift Data Output
	TxDC1	02	St/B	CAN Node 1 Transmit Data Output
	CCU61_ COUT63	О3	St/B	CCU61 Channel 3 Output
	A6	ОН	St/B	External Bus Interface Address Line 6
	U1C1_DX0A	1	St/B	USIC1 Channel 1 Shift Data Input
	CCU61_ CTRAPA	I	St/B	CCU61 Emergency Trap Input
	U1C1_DX1B	I	St/B	USIC1 Channel 1 Shift Clock Input
72	P10.6	O0 / I	St/B	Bit 6 of Port 10, General Purpose Input/Output
	U0C0_DOUT	01	St/B	USIC0 Channel 0 Shift Data Output
	TxDC4	O2	St/B	CAN Node 4 Transmit Data Output
	U1C0_ SELO0	О3	St/B	USIC1 Channel 0 Select/Control 0 Output
	AD6	OH/I	St/B	External Bus Interface Address/Data Line 6
	U0C0_DX0C	I	St/B	USIC0 Channel 0 Shift Data Input
	U1C0_DX2D	I	St/B	USIC1 Channel 0 Shift Control Input
	CCU60_ CTRAPA	I	St/B	CCU60 Emergency Trap Input
73	P10.7	O0 / I	St/B	Bit 7 of Port 10, General Purpose Input/Output
	U0C1_DOUT	01	St/B	USIC0 Channel 1 Shift Data Output
	CCU60_ COUT63	O2	St/B	CCU60 Channel 3 Output
	AD7	OH/I	St/B	External Bus Interface Address/Data Line 7
	U0C1_DX0B	I	St/B	USIC0 Channel 1 Shift Data Input
	CCU60_ CCPOS0A	1	St/B	CCU60 Position Input 0
	RxDC4C	1	St/B	CAN Node 4 Receive Data Input

General Device Information

 Table 4
 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Туре	Function
83	P10.11	O0 / I	St/B	Bit 11 of Port 10, General Purpose Input/Output
	U1C0_ SCLKOUT	01	St/B	USIC1 Channel 0 Shift Clock Output
	BRKOUT	O2	St/B	OCDS Break Signal Output
	AD11	OH/I	St/B	External Bus Interface Address/Data Line 11
	U1C0_DX1D	I	St/B	USIC1 Channel 0 Shift Clock Input
	RxDC2B	I	St/B	CAN Node 2 Receive Data Input
	TMS_B	I	St/B	JTAG Test Mode Selection Input
84	P1.2	O0 / I	St/B	Bit 2 of Port 1, General Purpose Input/Output
	CCU62_ CC62	O1 / I	St/B	CCU62 Channel 2 Input/Output
	U1C0_ SELO6	O2	St/B	USIC1 Channel 0 Select/Control 6 Output
	U2C1_ SCLKOUT	O3	St/B	USIC2 Channel 1 Shift Clock Output
	A10	ОН	St/B	External Bus Interface Address Line 10
	ESR1_4	I	St/B	ESR1 Trigger Input 4
	CCU61_ T12HRB	I	St/B	External Run Control Input for T12 of CCU61
	EX2AINA	I	St/B	External Interrupt Trigger Input
	U2C1_DX0D	I	St/B	USIC2 Channel 1 Shift Data Input
	U2C1_DX1C	I	St/B	USIC2 Channel 1 Shift Clock Input
85	P10.12	O0 / I	St/B	Bit 12 of Port 10, General Purpose Input/Output
	U1C0_DOUT	01	St/B	USIC1 Channel 0 Shift Data Output
	TxDC2	O2	St/B	CAN Node 2 Transmit Data Output
	TDO_B	О3	St/B	JTAG Test Data Output
	AD12	OH/I	St/B	External Bus Interface Address/Data Line 12
	U1C0_DX0C	I	St/B	USIC1 Channel 0 Shift Data Input
	U1C0_DX1E	I	St/B	USIC1 Channel 0 Shift Clock Input



Functional Description

With this hardware most XC226x instructions can be executed in a single machine cycle of 12.5 ns with an 80-MHz CPU clock. For example, shift and rotate instructions are always processed during one machine cycle, no matter how many bits are shifted. Also, multiplication and most MAC instructions execute in one cycle. All multiple-cycle instructions have been optimized so that they can be executed very fast; for example, a 32-/16-bit division is started within 4 cycles while the remaining cycles are executed in the background. Another pipeline optimization, the branch target prediction, eliminates the execution time of branch instructions if the prediction was correct.

The CPU has a register context consisting of up to three register banks with 16 word-wide GPRs each at its disposal. One of these register banks is physically allocated within the on-chip DPRAM area. A Context Pointer (CP) register determines the base address of the active register bank accessed by the CPU at any time. The number of these register bank copies is only restricted by the available internal RAM space. For easy parameter passing, a register bank may overlap others.

A system stack of up to 32 Kwords is provided for storage of temporary data. The system stack can be allocated to any location within the address space (preferably in the on-chip RAM area); it is accessed by the CPU with the stack pointer (SP) register. Two separate SFRs, STKOV and STKUN, are implicitly compared with the stack pointer value during each stack access to detect stack overflow or underflow.

The high performance of the CPU hardware implementation can be best utilized by the programmer with the highly efficient XC226x instruction set. This includes the following instruction classes:

- Standard Arithmetic Instructions
- DSP-Oriented Arithmetic Instructions
- Logical Instructions
- Boolean Bit Manipulation Instructions
- Compare and Loop Control Instructions
- Shift and Rotate Instructions
- Prioritize Instruction
- Data Movement Instructions
- System Stack Instructions
- Jump and Call Instructions
- Return Instructions
- System Control Instructions
- Miscellaneous Instructions

The basic instruction length is either 2 or 4 bytes. Possible operand types are bits, bytes and words. A variety of direct, indirect or immediate addressing modes are provided to specify the required operands.

Data Sheet 37 V2.1, 2008-08



Functional Description

When a capture/compare register has been selected for capture mode, the current contents of the allocated timer will be latched ('captured') into the capture/compare register in response to an external event at the port pin associated with this register. In addition, a specific interrupt request for this capture/compare register is generated. Either a positive, a negative, or both a positive and a negative external signal transition at the pin can be selected as the triggering event.

The contents of all registers selected for one of the five compare modes are continuously compared with the contents of the allocated timers.

When a match occurs between the timer value and the value in a capture/compare register, specific actions will be taken based on the compare mode selected.

Data Sheet 46 V2.1, 2008-08



Functional Description

MultiCAN Features

- CAN functionality conforming to CAN specification V2.0 B active for each CAN node (compliant to ISO 11898)
- Up to five independent CAN nodes
- Up to 128 independent message objects (shared by the CAN nodes)
- · Dedicated control registers for each CAN node
- Data transfer rate up to 1 Mbit/s, individually programmable for each node
- · Flexible and powerful message transfer control and error handling capabilities
- Full-CAN functionality for message objects:
 - Can be assigned to one of the CAN nodes
 - Configurable as transmit or receive objects, or as message buffer FIFO
 - Handle 11-bit or 29-bit identifiers with programmable acceptance mask for filtering
 - Remote Monitoring Mode, and frame counter for monitoring
- Automatic Gateway Mode support
- 16 individually programmable interrupt nodes
- Analyzer mode for CAN bus monitoring



Functional Description

3.13 Watchdog Timer

The Watchdog Timer is one of the fail-safe mechanisms which have been implemented to prevent the controller from malfunctioning for longer periods of time.

The Watchdog Timer is always enabled after an application reset of the chip. It can be disabled and enabled at any time by executing the instructions DISWDT and ENWDT respectively. The software has to service the Watchdog Timer before it overflows. If this is not the case because of a hardware or software failure, the Watchdog Timer overflows, generating a prewarning interrupt and then a reset request.

The Watchdog Timer is a 16-bit timer clocked with the system clock divided by 16,384 or 256. The Watchdog Timer register is set to a prespecified reload value (stored in WDTREL) in order to allow further variation of the monitored time interval. Each time it is serviced by the application software, the Watchdog Timer is reloaded and the prescaler is cleared.

Time intervals between 3.2 μ s and 13.4 s can be monitored (@ 80 MHz). The default Watchdog Timer interval after power-up is 6.5 ms (@ 10 MHz).

3.14 Clock Generation

The Clock Generation Unit can generate the system clock signal f_{SYS} for the XC226x from a number of external or internal clock sources:

- External clock signals with pad or core voltage levels
- External crystal using the on-chip oscillator
- On-chip clock source for operation without crystal
- Wake-up clock (ultra-low-power) to further reduce power consumption

The programmable on-chip PLL with multiple prescalers generates a clock signal for maximum system performance from standard crystals or from the on-chip clock source. See also **Section 4.6.2**.

The Oscillator Watchdog (OWD) generates an interrupt if the crystal oscillator frequency falls below a certain limit or stops completely. In this case, the system can be supplied with an emergency clock to enable operation even after an external clock failure.

All available clock signals can be output on one of two selectable pins.

Data Sheet 61 V2.1, 2008-08



Functional Description

3.15 Parallel Ports

The XC226x provides up to 75 I/O lines which are organized into 7 input/output ports and 2 input ports. All port lines are bit-addressable, and all input/output lines can be individually (bit-wise) configured via port control registers. This configuration selects the direction (input/output), push/pull or open-drain operation, activation of pull devices, and edge characteristics (shape) and driver characteristics (output current) of the port drivers. The I/O ports are true bidirectional ports which are switched to high impedance state when configured as inputs. During the internal reset, all port pins are configured as inputs without pull devices active.

All port lines have alternate input or output functions associated with them. These alternate functions can be programmed to be assigned to various port pins to support the best utilization for a given application. For this reason, certain functions appear several times in **Table 9**.

All port lines that are not used for alternate functions may be used as general purpose I/O lines.

Table 9 Summary of the XC226x's Parallel Ports

Port	Width	Alternate Functions
Port 0	8	Address lines, Serial interface lines of USIC1, CAN0, and CAN1, Input/Output lines for CCU61
Port 1	8	Address lines, Serial interface lines of USIC1 and USIC2, Input/Output lines for CCU62, OCDS control, interrupts
Port 2	13	Address and/or data lines, bus control, Serial interface lines of USIC0, CAN0, and CAN1, Input/Output lines for CCU60, CCU63, and CAPCOM2, Timer control signals, JTAG, interrupts, system clock output
Port 4	8	Chip select signals, Serial interface lines of CAN2, Input/Output lines for CAPCOM2, Timer control signals
Port 5	16	Analog input channels to ADC0, Input/Output lines for CCU6x, Timer control signals, JTAG, OCDS control, interrupts



Pullup/Pulldown Device Behavior

Most pins of the XC226x feature pullup or pulldown devices. For some special pins these are fixed; for the port pins they can be selected by the application.

The specified current values indicate how to load the respective pin depending on the intended signal level. **Figure 12** shows the current paths.

The shaded resistors shown in the figure may be required to compensate system pull currents that do not match the given limit values.

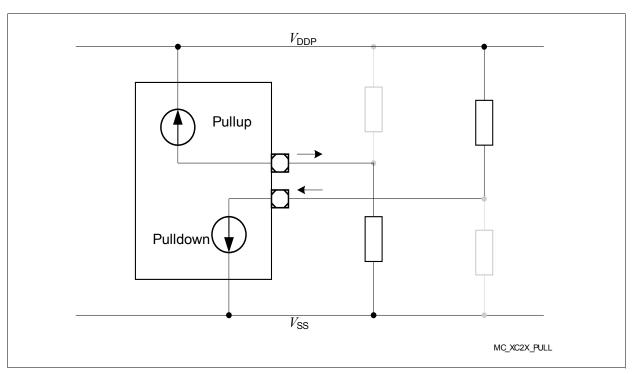


Figure 12 Pullup/Pulldown Current Definition

Data Sheet 73 V2.1, 2008-08



Table 18 A/D Converter Characteristics (cont'd) (Operating Conditions apply)

Parameter	Symbol		Lim	it Values	Unit	Test	
			Min.	Max.		Condition	
Switched capacitance of the reference input	C_{AREFS}	CC	_	7	pF	6)7)	
Resistance of the reference input path	R_{AREF}	CC	_	2	kΩ	6)7)	

- 1) TUE is tested at $V_{\text{AREFx}} = V_{\text{DDPA}}$, $V_{\text{AGND}} = 0 \text{ V}$. It is verified by design for all other voltages within the defined voltage range.
 - The specified TUE is valid only if the absolute sum of input overload currents on Port 5 or Port 15 pins (see $I_{\rm OV}$ specification) does not exceed 10 mA, and if $V_{\rm AREF}$ and $V_{\rm AGND}$ remain stable during the measurement time.
- 2) V_{AIN} may exceed V_{AGND} or V_{AREFx} up to the absolute maximum ratings. However, the conversion result in these cases will be X000_H or X3FF_H, respectively.
- 3) The limit values for f_{ADCI} must not be exceeded when selecting the peripheral frequency and the prescaler setting.
- 4) This parameter includes the sample time (also the additional sample time specified by STC), the time to determine the digital result and the time to load the result register with the conversion result. Values for the basic clock t_{ADCI} depend on programming and are found in Table 19.
- 5) The total unadjusted error TUE is the maximum deviation from the ideal ADC transfer curve, not the sum of individual errors.
 - All error specifications are based on measurement methods standardized by IEEE 1241.2000.
- 6) Not subject to production test verified by design/characterization.
- 7) These parameter values cover the complete operating range. Under relaxed operating conditions (temperature, supply voltage) typical values can be used for calculation. At room temperature and nominal supply voltage the following typical values can be used:

$$C_{\mathsf{AINTtyp}}$$
 = 12 pF, C_{AINStyp} = 5 pF, R_{AINtyp} = 1.0 k Ω , C_{AREFTtyp} = 15 pF, C_{AREFStyp} = 10 pF, R_{AREFtyp} = 1.0 k Ω .

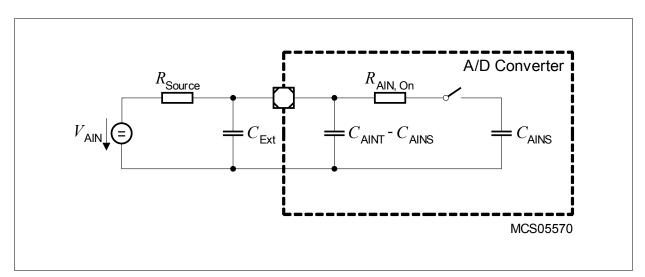


Figure 15 Equivalent Circuitry for Analog Inputs

Data Sheet 84 V2.1, 2008-08



Sample time and conversion time of the XC226x's A/D converters are programmable. The timing above can be calculated using **Table 19**.

The limit values for f_{ADCI} must not be exceeded when selecting the prescaler value.

Table 19 A/D Converter Computation Table

GLOBCTR.5-0 (DIVA)	A/D Converter Analog Clock f_{ADCI}	INPCRx.7-0 (STC)	Sample Time $t_{\rm S}$
000000 _B	$f_{ exttt{SYS}}$	00 _H	$t_{ADCI} \times 2$
000001 _B	f_{SYS} / 2	01 _H	$t_{ADCI} \times 3$
000010 _B	f_{SYS} / 3	02 _H	$t_{ADCI} \times 4$
:	$f_{\rm SYS}$ / (DIVA+1)	:	$t_{ADCI} \times (STC+2)$
111110 _B	f _{SYS} / 63	FE _H	$t_{ADCI} \times 256$
111111 _B	f _{SYS} / 64	FF _H	$t_{ADCI} imes 257$

Converter Timing Example A:

Assumptions: f_{SYS} = 80 MHz (i.e. t_{SYS} = 12.5 ns), DIVA = 03_H, STC = 00_H

Analog clock $f_{ADCI} = f_{SYS} / 4 = 20 \text{ MHz}$, i.e. $t_{ADCI} = 50 \text{ ns}$

Sample time $t_S = t_{ADCI} \times 2 = 100 \text{ ns}$

Conversion 10-bit:

 $t_{\text{C10}} = 13 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 13 \times 50 \text{ ns} + 2 \times 12.5 \text{ ns} = 0.675 \text{ }\mu\text{s}$

Conversion 8-bit:

 $t_{\rm C8} = 11 \times t_{\rm ADCI} + 2 \times t_{\rm SYS} = 11 \times 50 \text{ ns} + 2 \times 12.5 \text{ ns} = 0.575 \text{ }\mu\text{s}$

Converter Timing Example B:

Assumptions: f_{SYS} = 40 MHz (i.e. t_{SYS} = 25 ns), DIVA = 02_H, STC = 03_H

Analog clock $f_{ADCI} = f_{SYS} / 3 = 13.3 \text{ MHz}$, i.e. $t_{ADCI} = 75 \text{ ns}$

Sample time $t_{\rm S} = t_{\rm ADCI} \times 5 = 375 \text{ ns}$

Conversion 10-bit:

 $t_{\text{C10}} = 16 \times t_{\text{ADCI}} + 2 \times t_{\text{SYS}} = 16 \times 75 \text{ ns} + 2 \times 25 \text{ ns} = 1.25 \text{ }\mu\text{s}$

Conversion 8-bit:

 t_{C8} = 14 × t_{ADCI} + 2 × t_{SYS} = 14 × 75 ns + 2 × 25 ns = 1.10 μ s

Data Sheet 85 V2.1, 2008-08



4.4 System Parameters

The following parameters specify several aspects which are important when integrating the XC226x into an application system.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Table 20 Various System Parameters

Parameter	Symbol		Values	S	Unit	Note /	
		Min.	Тур.	Max.		Test Condition	
Supply watchdog (SWD) supervision level (see Table 21)	V _{SWD} CC	V _{LV} - 0.150	V_{LV}	V _{LV} + 0.100	V	$V_{\rm LV}$ = selected voltage in upper voltage area	
		V _{LV} - 0.125	V_{LV}	V _{LV} + 0.050	V	$V_{\rm LV}$ = selected voltage in lower voltage area	
Core voltage (PVC) supervision level (see Table 22)	$V_{PVC}CC$	V _{LV} - 0.070	V_{LV}	V _{LV} + 0.030	V	$V_{\rm LV}$ = selected voltage	
Current control limit	$I_{\rm CC}$ CC	13	_	30	mA	Power domain DMP_M	
		90	_	150	mA	Power domain DMP_1	
Wakeup clock source frequency	$f_{WU}CC$	400	500	600	kHz	FREQSEL = 00 _B	
Internal clock source frequency	$f_{INT}CC$	4.8	5.0	5.2	MHz		
Startup time from stopover mode	$t_{\rm SSO}$ CC	200	260	320	μs	User instruction from PSRAM	
Startup time from standby mode	t _{SSB} CC	2.5	2.8	3.5	ms	User instruction from Flash	



4.6 AC Parameters

These parameters describe the dynamic behavior of the XC226x.

4.6.1 Testing Waveforms

These values are used for characterization and production testing (except pin XTAL1).

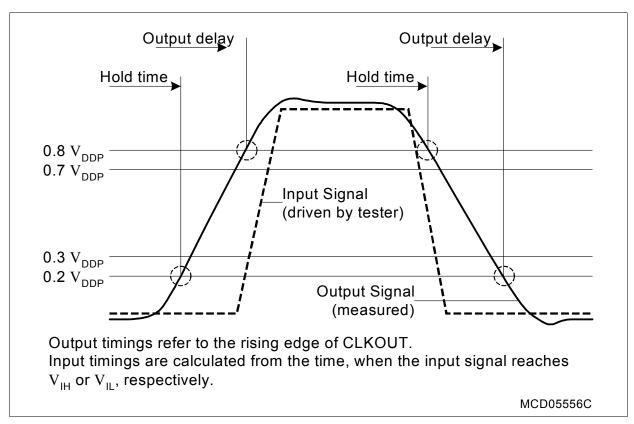
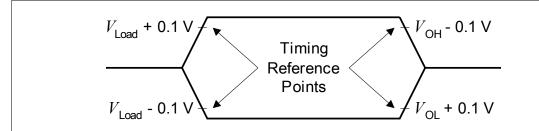


Figure 16 Input Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs, but begins to float when a 100 mV change from the loaded $V_{\rm OH}/V_{\rm OI}$ level occurs ($I_{\rm OH}/I_{\rm OI}$ = 20 mA).

MCA05565

Figure 17 Floating Waveforms



4.6.2 Definition of Internal Timing

The internal operation of the XC226x is controlled by the internal system clock f_{SYS} .

Because the system clock signal $f_{\rm SYS}$ can be generated from a number of internal and external sources using different mechanisms, the duration of the system clock periods (TCSs) and their variation (as well as the derived external timing) depend on the mechanism used to generate $f_{\rm SYS}$. This must be considered when calculating the timing for the XC226x.

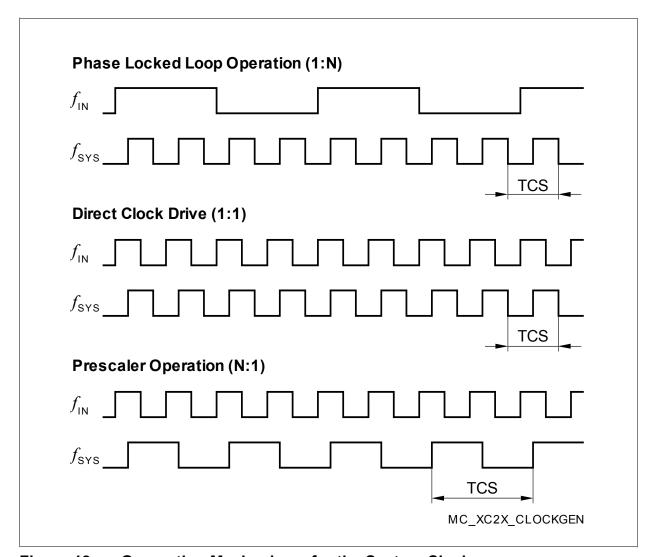


Figure 18 Generation Mechanisms for the System Clock

Note: The example of PLL operation shown in **Figure 18** uses a PLL factor of 1:4; the example of prescaler operation uses a divider factor of 2:1.

The specification of the external timing (AC Characteristics) depends on the period of the system clock (TCS).



4.6.3 External Clock Input Parameters

These parameters specify the external clock generation for the XC226x. The clock can be generated in two ways:

- By connecting a crystal or ceramic resonator to pins XTAL1/XTAL2.
- By supplying an external clock signal. This clock signal can be supplied either to pin XTAL1 (core voltage domain) or to pin CLKIN1 (IO voltage domain).

If connected to CLKIN1, the input signal must reach the defined input levels $V_{\rm IL}$ and $V_{\rm IH}$. In connected to XTAL1, a minimum amplitude $V_{\rm AX1}$ (peak-to-peak voltage) is sufficient for the operation of the on-chip oscillator.

Note: The given clock timing parameters $(t_1 \dots t_4)$ are only valid for an external clock input signal.

Table 26 External Clock Input Characteristics (Operating Conditions apply)

Parameter	Symbol	L	imit Val	ues	Unit	Note / Test
		Min.	Тур.	Max.		Condition
Input voltage range limits for signal on XTAL1	$V_{\rm IX1}{ m SR}$	-1.7 + V _{DDI}	_	1.7	V	1)
Input voltage (amplitude) on XTAL1	$V_{AX1}SR$	$0.3 \times V_{\mathrm{DDI}}$	_	_	V	Peak-to-peak voltage ²⁾
XTAL1 input current	I_{IL} CC	_	_	±20	μΑ	$0 \ V < V_{IN} < V_{DD}$
Oscillator frequency	$f_{\rm OSC}$ CC	4	_	40	MHz	Clock signal
		4	_	16	MHz	Crystal or Resonator
High time	t ₁ SR	6	_	_	ns	
Low time	t ₂ SR	6	_	_	ns	
Rise time	t ₃ SR	_	8	8	ns	
Fall time	t ₄ SR	_	8	8	ns	

¹⁾ Overload conditions must not occur on pin XTAL1.

Data Sheet 96 V2.1, 2008-08

²⁾ The amplitude voltage V_{AX1} refers to the offset voltage V_{OFF} . This offset voltage must be stable during the operation and the resulting voltage peaks must remain within the limits defined by V_{IX1} .



4.6.4 External Bus Timing

The following parameters specify the behavior of the XC226x bus interface.

Table 27 CLKOUT Reference Signal

Parameter	Sym	Symbol		Limits	Unit	Note / Test Condition
				Max.		
CLKOUT cycle time	t_5	CC	40	/25/12.5 ¹⁾	ns	
CLKOUT high time	<i>t</i> ₆	CC	3	_	ns	
CLKOUT low time	<i>t</i> ₇	CC	3	_	ns	
CLKOUT rise time	<i>t</i> ₈	CC	_	3	ns	
CLKOUT fall time	t_9	CC	_	3	ns	

¹⁾ The CLKOUT cycle time is influenced by the PLL jitter (given values apply to $f_{\rm SYS}$ = 25/40/80 MHz). For longer periods the relative deviation decreases (see PLL deviation formula).

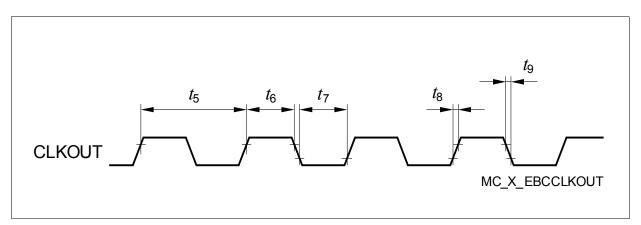


Figure 21 CLKOUT Signal Timing

Note: The term CLKOUT refers to the reference clock output signal which is generated by selecting f_{SYS} as the source signal for the clock output signal EXTCLK on pin P2.8 and by enabling the high-speed clock driver on this pin.

Data Sheet 98 V2.1, 2008-08

4.6.5 Synchronous Serial Interface Timing

The following parameters are applicable for a USIC channel operated in SSC mode.

Note: These parameters are not subject to production test but verified by design and/or characterization.

Table 31 SSC Master/Slave Mode Timing for Upper Voltage Range (Operating Conditions apply), $C_1 = 50 \text{ pF}$

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Co ndition
Master Mode Timing		1		- "		
Slave select output SELO active to first SCLKOUT transmit edge	t ₁ CC	0	_	1)	ns	2)
Slave select output SELO inactive after last SCLKOUT receive edge	t ₂ CC	$0.5 \times t_{BIT}$	_	3)	ns	
Transmit data output valid time	t ₃ CC	-6	_	13	ns	
Receive data input setup time to SCLKOUT receive edge	t ₄ SR	31	-	_	ns	
Data input DX0 hold time from SCLKOUT receive edge	t ₅ SR	-7	_	_	ns	
Slave Mode Timing					- 1	
Select input DX2 setup to first clock input DX1 transmit edge	<i>t</i> ₁₀ SR	7	_	_	ns	4)
Select input DX2 hold after last clock input DX1 receive edge	<i>t</i> ₁₁ SR	5	_	_	ns	4)
Data input DX0 setup time to clock input DX1 receive edge	<i>t</i> ₁₂ SR	7	_	_	ns	4)
Data input DX0 hold time from clock input DX1 receive edge	<i>t</i> ₁₃ SR	5	_	-	ns	4)
Data output DOUT valid time	t ₁₄ CC	8	_	29	ns	4)

¹⁾ The maximum value further depends on the settings for the slave select output leading delay.

Data Sheet 106 V2.1, 2008-08

²⁾ $t_{SYS} = 1/f_{SYS}$ (= 12.5 ns @ 80 MHz)

³⁾ The maximum value depends on the settings for the slave select output trailing delay and for the shift clock output delay.

⁴⁾ These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).